

WHAT IS CLAIMED IS:

1. A multilayer electronic component comprising:
an electronic component body containing dielectric layers and internal electrode
layers that are alternatively laminated, said internal electrode layers being exposed
5 alternatively to end faces on opposite sides along a laminating direction; and
external electrodes disposed on both end faces of said electronic component body
and connected to said internal electrode layers,
wherein a thickness of a connecting end of said internal electrode layers with said
external electrodes is greater than a thickness of a non-connecting end.
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2. The multilayer electronic component according to claim 1 wherein internal
electrode layers are gradually thinned from a connecting end with external electrodes to a
non-connecting end.
- 15 3. The multilayer electronic component according to claim 1 wherein an
average thickness of internal electrode layers is 1 μm or less.
4. The multilayer electronic component according to claim 1 wherein a
thickness of dielectric layers is 5 μm or less.
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5. The multilayer electronic component according to claim 1, satisfying the
relationship of $(L/t) \geq 500$, where L is a distance from a connecting end of internal electrode
layers to a non-connecting end, and t is a maximum thickness of said internal electrode
layers.
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6. The multilayer electronic component according to one of claims 1, wherein

internal electrode layers are formed by an electroplating film.

7. The multilayer electronic component according to claim 1 wherein internal electrode layers are composed of a base metal.

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8. The multilayer electronic component according to claim 1 wherein said internal electrode layers contain a base metal material and at least one element selected from Groups 3b to 6b elements in the periodic table.

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9. The multilayer electronic component according to claim 8 wherein at least one element selected from Groups 3b to 6b elements in the periodic table is sulfur.

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10. The multilayer electronic component according to claim 8 wherein the amount of content of Groups 3b to 6b elements in the periodic table is in a range of 5 to 2000 $\mu\text{g/g}$ to internal electrode layers.

11. The multilayer electronic component according to claim 1 wherein internal electrode layers have extending parts on a connecting end with said external electrodes.

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12. The multilayer electronic component according to claim 11 wherein extending parts are connected to each other.

13. A method of manufacturing a multilayer electronic component comprising the steps of:

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preparing a substrate plate having a mask pattern;

performing electroplating in a state in which said substrate plate is tilted such that

said mask pattern faces downwardly, so that an internal electrode pattern whose edges have different thicknesses is formed in a recess part partitioned by said mask pattern on the surface of said substrate plate;

transferring said internal electrode pattern on the surface of said substrate plate, to
5 a dielectric green sheet;

forming a lamination forming body by laminating such that a total thickness of edges of said internal electrode pattern is compensated for in a laminating direction; and

forming an electronic component base forming body in which one edge of said internal electrode pattern is exposed by cutting said lamination forming body in a
10 laminating direction.

14. The method according to claim 13 wherein an internal electrode pattern is gradually thinned from an exposed edge to an unexposed edge.

15 15. The method according to claim 13 wherein an average thickness of an internal electrode pattern is 1 μm or less.

16. The method according to claim 13 wherein a main component of an internal electrode pattern in a base metal.

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17. The method according to claim 13 wherein an internal electrode pattern contains a base metal material and at least one element selected from Groups 3b to 6b elements in the periodic table.

25 18. A multilayer electronic component comprising:
an electronic component body having a capacity part developing electrostatic

capacity which is formed by alternatively laminating dielectric layers and internal electrode layers, and a non-capacity part not developing electrostatic capacity which is disposed around the periphery of said capacity part and formed by said dielectric layers; and

a pair of external electrodes disposed on both end faces of said electronic
5 component body, respectively, and connected to said internal electrode layers,

wherein said electronic component body has on both end faces thereof an
extending part continuous from said internal electrode layers.

19. The multilayer electronic component according to claim 18 wherein
10 extending parts are connected to each other at end faces of said electronic component body.